



**NOTES:**

1. INSULATION BOARDS MUST BE PLACED INTO THE ADHESIVE AS SOON AS IT STARTS TO FOAM (WITHIN 15 SECONDS). STEP BOARDS INTO PLACE. DO NOT REPOSITION BOARDS ONCE THEY ARE SET. DO NOT PUDDLE OR MOUND THE ADHESIVE AS THIS CAN LEAD TO EXCESSIVE RISE AND BOARD SURFACE UNEVENNESS.
2. IDEAL AMBIENT TEMPERATURE FOR APPLICATION IS 45° AND RISING. MATERIAL TEMPERATURE MUST BE BETWEEN 70°F AND 85°F.
3. APPLY ADHESIVE AT 12" O.C. AT THE FIELD OF THE ROOF (4 BEADS PER BOARD).
4. APPLY ADHESIVE AT 6" O.C. IN PERIMETER AREAS (8 BEADS PER BOARD) AND 4" O.C. IN CORNER AREAS (12 BEADS PER BOARD).



SHEET TITLE:

**TREMCO LOW RISE FOAM INSULATION  
ADHESIVE APPLICATION METAL DECK**

SCALE:

**NTS**

DRAWING No.:

**DWG NO. TLRFIA-02**